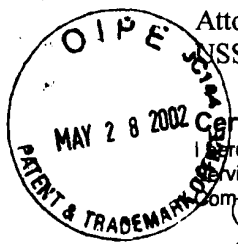


2811



Attorney Docket No.: CPAC 1003-1 US
ISSN 09/802,664

PATENT

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Linda Shaw
Linda Shaw

May 10, 2002
Date

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)
Rajendra D. Pendse)
) Examiner: Unknown
Application No.: 09/802,664)
) Group Art Unit: 2811
Filed: March 9, 2001)
) Date: May 10, 2002
Title: Flip chip interconnection)
structure)
)

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SEPARATE LETTER TO OFFICIAL DRAFTSPERSON

Official Draftsperson
Commissioner Of Patents
Washington, D.C. 20231

Official Draftsperson:

In connection with the above-referenced U. S. patent application, transmitted herewith are the following papers:

- ☒ Three (3) sheets of formal drawing(s) (Figs 1A, 1B, 2A, 2B, 3A, 3B, 4A, 4B, 5 and 6).

Authorization is hereby given to deduct from or credit to Deposit Account No. 50-0869 (CPAC 1003-1 US), any additional fees that may be required with this matter. A duplicate copy of this paper is enclosed.

Respectfully submitted,
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